**BRING UP PLAN**

Integrated Accelerometer Board

1. Verify fabrication by checking each copper trace with a DMM.
2. Verify the power pins are connected to the correct planes using a DMM. Each power plane (1.5V, 3.3V, and Ground) should be connected to the components demanding these voltages.
3. Align PCB with stencil to apply solder paste.
4. Gather components from supplier and organize them for placement.
5. Verify orientation of components on solder mask.
6. Carefully place components on the backside of the PCB first. This side just has an accelerometer and a capacitor.
7. Reflow the PCB.
8. Inspect joints.
9. Carefully place components on the frontside of the board.
10. Reflow the PCB.
11. Inspect new joints.
12. Perform continuity testing on the board using a DMM.
13. Verify that the power electronics subsystem outputs the correct voltages to the 1.5V and 3.3V pins.
14. Solder the rest of the through-hole components.